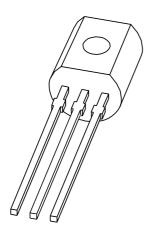
## **DISCRETE SEMICONDUCTORS**

# DATA SHEET



PBSS8110AS 100 V, 1 A NPN low V<sub>CEsat</sub> (BISS) transistor

Product specification Supersedes data of 2003 Nov 11

2003 Dec 03





# 100 V, 1 A NPN low V<sub>CEsat</sub> (BISS) transistor

### **PBSS8110AS**

#### **FEATURES**

- SOT54 package
- Low collector-emitter saturation voltage V<sub>CEsat</sub>
- High collector current capability: I<sub>C</sub> and I<sub>CM</sub>
- Higher efficiency leading to less heat generation.

#### **APPLICATIONS**

- Automotive 42 V power
- · Telecom infrastructure
- · General industrial applications
- Power management
  - DC/DC converters
  - Supply line switching
  - Battery charger
  - LCD backlighting.
- · Peripheral drivers
  - Generic driver (e.g. lamps and LEDs)
  - Inductive load driver (e.g. relays, buzzers and motors).

#### **DESCRIPTION**

NPN low  $V_{\text{CEsat}}$  BISS transistor in a SOT54 plastic package.

#### **QUICK REFERENCE DATA**

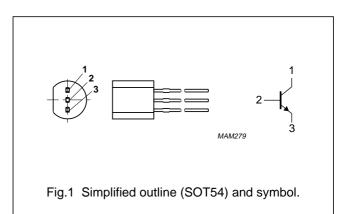
SYMBOL	PARAMETER	MAX.	UNIT
V <sub>CEO</sub>	collector-emitter voltage	100	V
I <sub>C</sub>	collector current (DC)	1	Α
I <sub>CM</sub>	peak collector current	3	Α
R <sub>CEsat</sub>	equivalent on-resistance	200	mΩ

#### **MARKING**

TYPE NUMBER	MARKING CODE
PBSS8110AS	S8110AS

#### **PINNING**

PIN	DESCRIPTION
1	collector
2	base
3	emitter



#### **ORDERING INFORMATION**

TYPE NUMBER		PACKAGE				
TIPE NOWIBER	NAME	DESCRIPTION	VERSION			
PBSS8110AS	_	plastic single-ended leaded (through hole) package; 3 leads	SOT54			

Philips Semiconductors Product specification

# 100 V, 1 A NPN low V<sub>CEsat</sub> (BISS) transistor

PBSS8110AS

#### **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	_	120	V
V <sub>CEO</sub>	collector-emitter voltage	open base	_	100	V
V <sub>EBO</sub>	emitter-base voltage	open collector	_	5	V
I <sub>C</sub>	collector current (DC)		_	1	Α
I <sub>CM</sub>	peak collector current	T <sub>j max</sub>	_	3	Α
I <sub>B</sub>	base current (DC)		_	300	mA
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C; note 1	_	830	mW
Tj	junction temperature		_	150	°C
T <sub>amb</sub>	operating ambient temperature		-65	+150	°C
T <sub>stg</sub>	storage temperature		-65	+150	°C

#### Note

1. Device mounted on a FR4 printed-circuit board; single-sided copper; tinplated; standard footprint.

#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	in free air; note 1	150	K/W

#### Note

1. Device mounted on a FR4 printed-circuit board; single-sided copper; tinplated; standard footprint.

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# 100 V, 1 A NPN low V<sub>CEsat</sub> (BISS) transistor

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#### **CHARACTERISTICS**

 $T_j = 25$  °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I <sub>CBO</sub>	collector cut-off current	V <sub>CB</sub> = 80 V; I <sub>E</sub> = 0	_	_	100	nA
		V <sub>CB</sub> = 80 V; I <sub>E</sub> = 0; T <sub>j</sub> = 150 °C	_	_	50	μΑ
I <sub>CES</sub>	collector cut-off current	V <sub>CE</sub> = 80 V; V <sub>BE</sub> = 0	_	_	100	nA
I <sub>EBO</sub>	emitter cut-off current	V <sub>EB</sub> = 4 V; I <sub>C</sub> = 0	_	_	100	nA
h <sub>FE</sub>	DC current gain	V <sub>CE</sub> = 10 V; I <sub>C</sub> = 1 mA	150	_	_	
		V <sub>CE</sub> = 10 V; I <sub>C</sub> = 250 mA	150	_	500	
		V <sub>CE</sub> = 10 V; I <sub>C</sub> = 0.5 A; note 1	100	_	_	
		V <sub>CE</sub> = 10 V; I <sub>C</sub> = 1 A; note 1	80	_	_	
V <sub>CEsat</sub>	collector-emitter saturation	I <sub>C</sub> = 100 mA; I <sub>B</sub> = 10 mA	_	_	40	mV
	voltage	I <sub>C</sub> = 500 mA; I <sub>B</sub> = 50 mA	_	_	120	mV
		I <sub>C</sub> = 1 A; I <sub>B</sub> = 100 mA	_	_	200	mV
R <sub>CEsat</sub>	equivalent on-resistance	I <sub>C</sub> = 1 A; I <sub>B</sub> = 100 mA; note 1	_	165	200	mΩ
V <sub>BEsat</sub>	base-emitter saturation voltage	I <sub>C</sub> = 1 A; I <sub>B</sub> = 100 mA; note 1	_	_	1.05	V
V <sub>BEon</sub>	base-emitter turn-on voltage	V <sub>CE</sub> = 10 V; I <sub>C</sub> = 1 A	_	_	0.9	V
f <sub>T</sub>	transition frequency	$V_{CE} = 10 \text{ V}; I_{C} = 50 \text{ mA}; f = 100 \text{ MHz}$	100	_	_	MHz
C <sub>c</sub>	collector capacitance	$V_{CB} = 10 \text{ V}; I_E = I_e = 0; f = 1 \text{ MHz}$	_	_	7.5	pF

#### Note

1. Pulse test:  $t_p \le 300~\mu s;~\delta \le 0.02.$ 

Philips Semiconductors Product specification

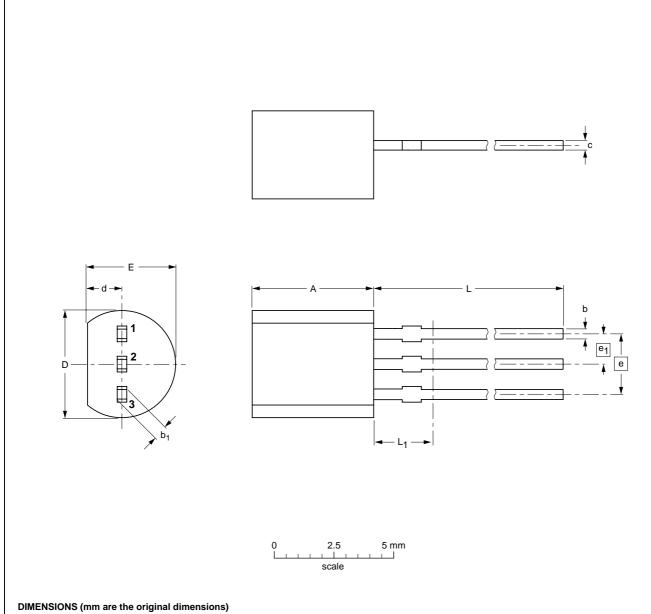
# 100 V, 1 A NPN low V<sub>CEsat</sub> (BISS) transistor

PBSS8110AS

#### **PACKAGE OUTLINE**

#### Plastic single-ended leaded (through hole) package; 3 leads

SOT54



UNIT	A	b	b <sub>1</sub>	С	D	d	E	е	e <sub>1</sub>	L	L <sub>1</sub> <sup>(1)</sup>
mm	5.2 5.0		0.66 0.56	0.45 0.40	4.8 4.4	1.7 1.4	4.2 3.6	2.54	1.27	14.5 12.7	2.5

1. Terminal dimensions within this zone are uncontrolled to allow for flow of plastic and terminal irregularities.

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT54		TO-92	SC-43			97-02-28

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## 100 V, 1 A NPN low V<sub>CEsat</sub> (BISS) transistor

### PBSS8110AS

#### **DATA SHEET STATUS**

LEVEL	DATA SHEET STATUS <sup>(1)</sup>	PRODUCT STATUS(2)(3)	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
II	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
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- 3. For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

#### **DEFINITIONS**

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Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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